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H8/300L SLP Series

Setting Standby Time to Cover Clock Stabilization

Introduction

This sample task shows how to set a standby time, during which the CPU and peripheral functions are kept in a standby state until the clock stabilizes.

Target Device

H8/38024

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1. Specifications

A standby time, during which the CPU and peripheral functions are kept in a standby state until the clock stabilizes, is set. This standby time is applied after a transition is made from standby mode or watch mode to active mode by means of a specific interrupt. The standby time must be set appropriately for the operating frequency so that it is longer than the clock oscillation stabilization time.

1.1 Setting the standby time

The standby time is set by setting the standby timer select bits 2 to 0 (STS2 to STS0) in system control register 1 (SYSCR1).

1.2 Description of the STS2 to STS0 bits

Table 1.1 describes the STS2 to STS0 bits in SYSCR1 register.

Table 1.1 Description of STS2 to STS0

SYSCR1

Bit 6	Bit 5	Bit 4	Description
STS2	STS1	STS0	
0	0	0	Standby time = 8,192 states (Initial value)
		1	Standby time = 16,384 states
	1	0	Standby time = 1,024 states
		1	Standby time = 2,048 states
1	0	0	Standby time = 4,096 states
		1	Standby time = 2 states (External clock mode)
	1	0	Standby time = 8 states
		1	Standby time = 16 states

Note: When an external clock signal is to be input, the standby timer select bits must be set to external clock mode before execution of the mode transition. When an external clock is not used, the external clock mode must not be set.

1.3 Operating frequency and oscillation stabilization time when a crystal oscillator is used

Table 1.2 shows the standby times for various operating frequencies and STS2 to STS0 settings. STS2 to STS0 must be set so that the standby time is longer than the time required for oscillation stabilization.

Table 1.2 Operating Frequency and Oscillation Stabilization Times

STS2	STS1	STS0	Standby Time	5 MHz	2 MHz
0	0	0	8,192 states	1.638	4.1
		1	16,384 states	3.277	8.2
	1	0	1,024 states	0.205	0.512
		1	2,048 states	0.410	1.024
1	0	0	4,092 states	0.819	2.048
		1	2 states (Use prohibited)	0.0004	0.001
	1	0	8 states	0.0002	0.004
		1	16 states	0.003	0.008

Unit: ms

1.4 When an external clock is used

Recommended setting is STS2 = 1, STS1 = 0, and STS0 = 1. Other settings are possible, but operation may start before the standby time ends.

1.5 Oscillation stabilization time

Table 1.3 shows the AC characteristics of oscillation stabilization times.

Table 1.3 AC Characteristics of Oscillation Stabilization Time

($V_{CC} = 1.8$ to 5.5 V, $AV_{CC} = 1.8$ to 5.5 V, $V_{SS} = AV_{SS} = 0.0$ V, $T_a = -20$ to $+75^\circ\text{C}$, including subactive mode)

Item	Symbol	Applicable Pins	Measurement Conditions	Values			Unit	Reference Figure
				Min	Typ	Max		
Oscillation stabilization time	t_{rc}	OSC ₁ , OSC ₂	$V_{CC} = 2.2$ V to 5.5 V (as shown in figure 1.1)	—	20	45	us	Figure 1.1
			Other than the above	—	—	50	ms	Figure 1.1
Oscillation stabilization time	t_{rc}	X ₁ , X ₂	$V_{CC} = 2.7$ V to 5.5 V	—	—	2.0	s	—
			$V_{CC} = 2.2$ V to 5.5 V	—	—	10.0	s	—

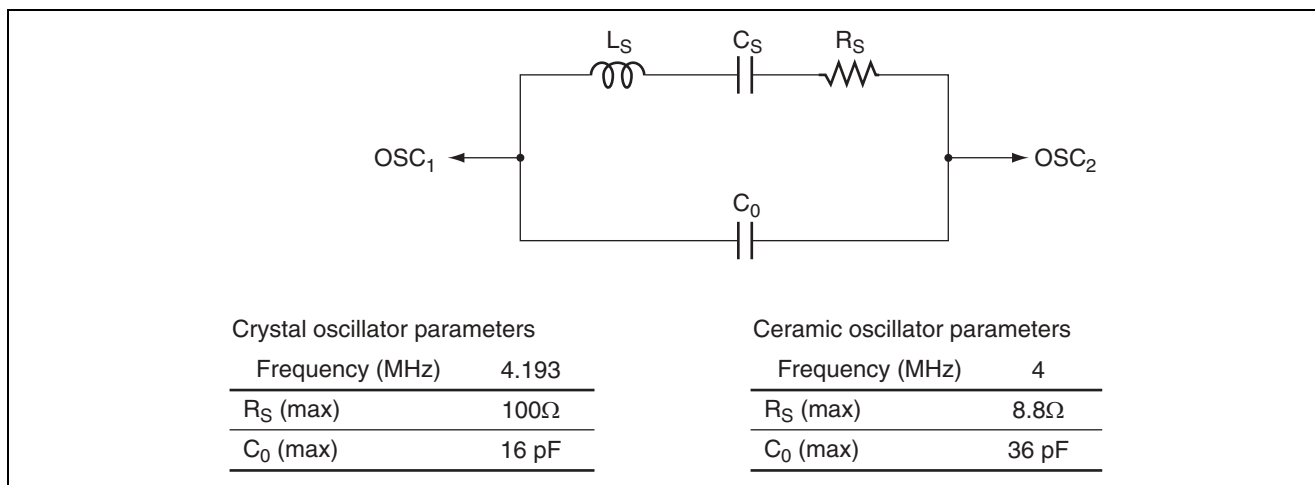


Figure 1.1 Oscillator Equivalent Circuit

1.6 Example of setting the standby time to cover clock stabilization

1. Functions

A transition from active (high-speed) to watch mode is induced. The watch mode is terminated after 250 ms by a timer A interrupt, and a transition is made to high-speed active mode. The standby time applied when returning from watch mode to high-speed active mode is set to eight states, during which the CPU and peripheral functions stay in a standby state waiting for the clock to stabilize.

2. Notes

In this example, when the watch mode is terminated by a timer A interrupt, timer A interrupt requests are disabled in timer A interrupt handling. Hence when a transition from high-speed active mode to watch mode is made, watch mode is then terminated by a timer A interrupt and high-speed active mode has been entered, the processing ends.

3. Watch mode

A. Transition to watch mode

In active mode or subactive mode, when the software standby bit (SSBY) in system control register 1 (SYSCR1) is 1 and the internal clock selector 3 bit (TMA3) in timer mode register A (TMA) is 1, executing a SLEEP instruction induces a transition to watch mode. In watch mode, operation of all on-chip peripheral functions other than timer A, timer F, timer G, the asynchronous event counter, and the LCD module (operation/halted selectable), is halted. As long as the rated voltage is supplied, the contents of CPU registers, some on-chip peripheral module registers, and on-chip RAM are retained. The I/O ports are held in the same states as before the transition.

B. Termination of watch mode

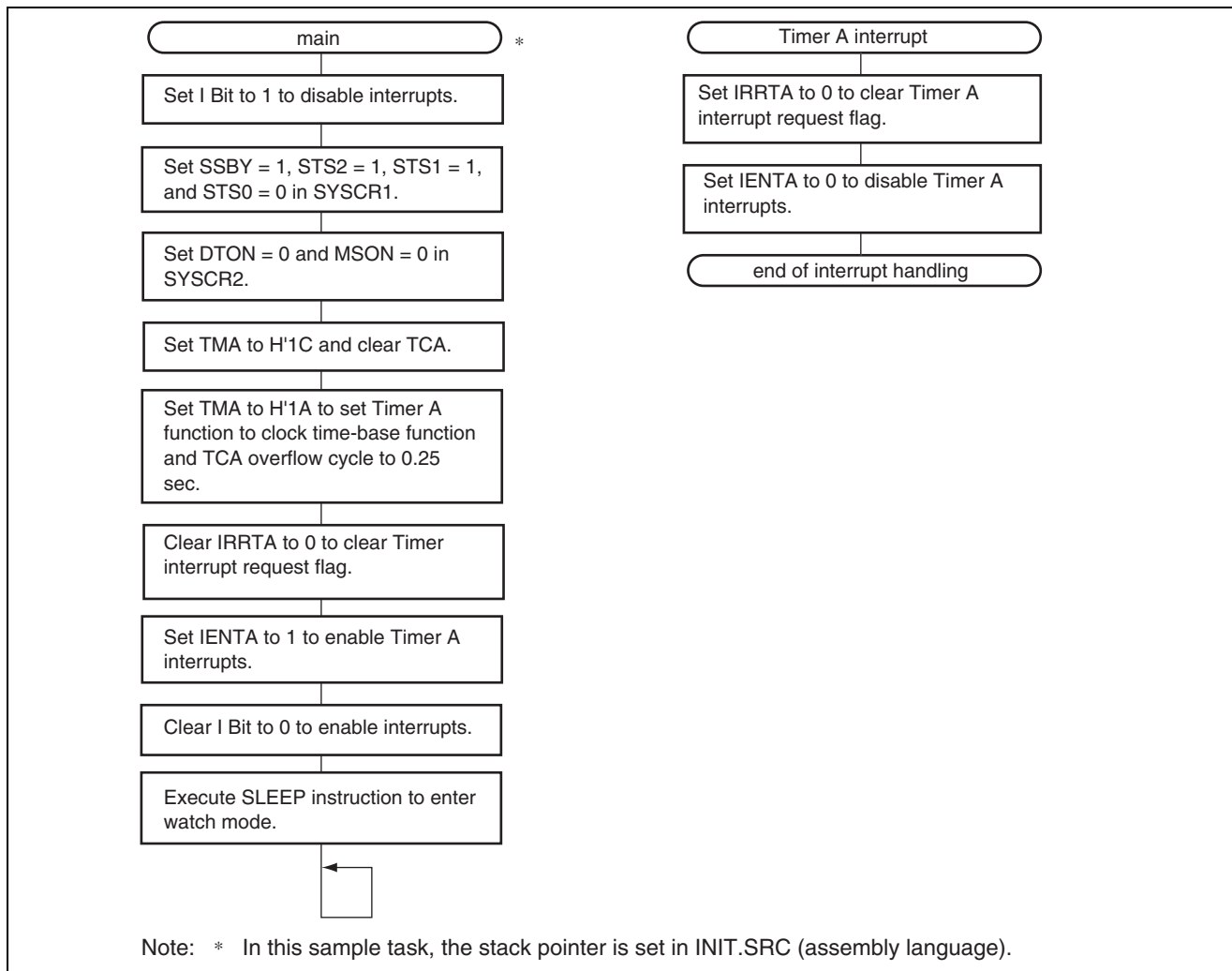
Watch mode is terminated by an interrupt (IRQ0, WKP7 to WKP0, timer A, timer F and timer G) or by RES pin input.

In the case of terminating the mode by an interrupt, the watch mode is terminated upon generation of a specific interrupt, and the system enters an operating mode according to the combination of the low-speed on-flag (LSON) in SYSCR1 and medium-speed on-flag (MSON) in system control register 2 (SYSCR2): high-speed active mode if LSON = 0 and MSON = 0, medium-speed active mode if LSON = 0 and MSON = 1, and subactive mode if LSON = 1. On transitions to active mode, after the time set by the STS2 to STS0 bits in SYSCR1 has elapsed, a stable clock signal is supplied to the entire LSI, and interrupt exception handling starts. When the I bit in CCR is 1 or when acceptance of the interrupt is disabled by the interrupt enable register, watch mode will not be terminated.

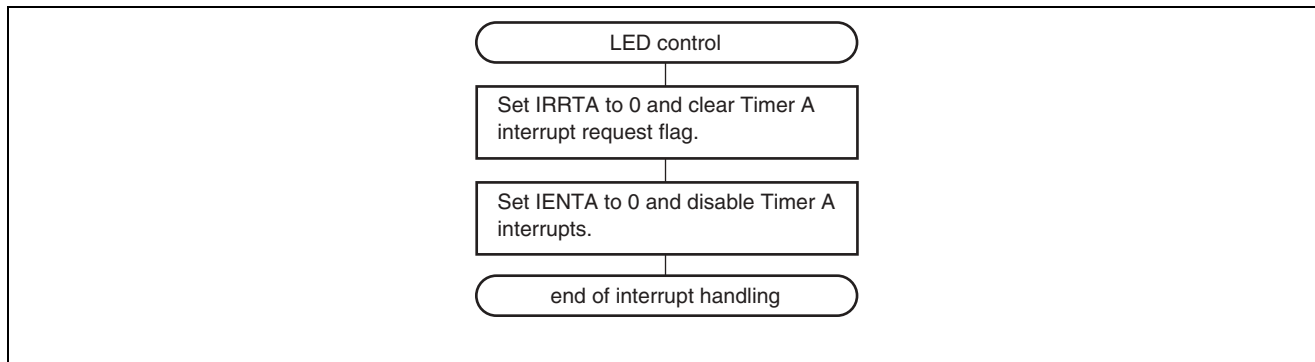
In the case of terminating the mode by the input on the RES pin, if the RES pin is driven low, system clock oscillation is started. After the time for oscillation stabilization has elapsed, if the RES pin is driven high, the CPU starts reset exception handling. The system clock is supplied to the entire LSI as soon as the system clock oscillation is started. The RES pin must be held at the low level until the system clock oscillation stabilizes.

2. Flowchart

1. Main routine



2. Timer A interrupt handling routine



3. Program Listing

INIT.SRC (Program listing)

```

.EXPORT  _INIT
.IMPORT  _main
;
.SECTION P, CODE
_INIT:
MOV.W   #H'FF80,R7
LDC.B   #B'10000000,CCR
JMP     @_main
;
.END

/*****
/*
/* H8/300L Super Low Power Series
/* -H8/38024 Series-
/* Application Note
/*
/* 'Oscillator Settling Time -8 States'
/*
/* Function
/* : Oscillator Settling Time
/*
/* External Clock : 0.8KHz
/* Internal Clock : 0.4KHz
/* Sub Clock      : 32.768kHz
/*
*****/

#include <machine.h>

/*****
/* Symbol Definition
*****/
struct BIT {
    unsigned char  b7:1;    /* bit7 */
    unsigned char  b6:1;    /* bit6 */
    unsigned char  b5:1;    /* bit5 */
    unsigned char  b4:1;    /* bit4 */
    unsigned char  b3:1;    /* bit3 */
    unsigned char  b2:1;    /* bit2 */
    unsigned char  b1:1;    /* bit1 */
    unsigned char  b0:1;    /* bit0 */
};

#define TMA      *(volatile unsigned char *)0xFFB0    /* Timer Mode Register A */
#define TCA      *(volatile unsigned char *)0xFFB1    /* Timer Counter A */
#define SYSCR1   *(volatile unsigned char *)0xFFFF0  /* System Control Register 1 */
#define SYSCR1_BIT (*(struct BIT *)0xFFFF0)          /* System Control Register 1 */
#define SSBY     SYSCR1_BIT.b7                        /* Software Standby */
#define STS2     SYSCR1_BIT.b6                        /* Standby Timer Select 2 */
#define STS1     SYSCR1_BIT.b5                        /* Standby Timer Select 1 */
#define STS0     SYSCR1_BIT.b4                        /* Standby Timer Select 0 */
#define LSON     SYSCR1_BIT.b3                        /* Low Speed On Flag */
#define MA1      SYSCR1_BIT.b1                        /* Active Mode Clock Select 1 */
#define MA0      SYSCR1_BIT.b0                        /* Active Mode Clock Select 0 */

```



```

#define SYSCR2      *(volatile unsigned char *)0xFFFF1      /* System Control Register 2      */
#define SYSCR2_BIT  (*(struct BIT *)0xFFFF1)                /* System Control Register 2      */
#define NESEL       SYSCR2_BIT.b4                            /* Noise Elimination Sampling     */
                                                           /*                               Frequency Select */
#define DTON        SYSCR2_BIT.b3                            /* Direct Transfer On Flag        */
#define MSON        SYSCR2_BIT.b2                            /* Middle Speed On Flag           */
#define SA1         SYSCR2_BIT.b1                            /* Subactive Mode Clock Select 1  */
#define SA0         SYSCR2_BIT.b0                            /* Subactive Mode Clock Select 0  */
#define IENR1_BIT  (*(struct BIT *)0xFFFF3)                /* Interrupt Enable Register 1    */
#define IENTA      IENR1_BIT.b7                             /* Timer A Interrupt Enable       */
#define IRR1_BIT   (*(struct BIT *)0xFFFF6)                /* Interrupt Request Register 1   */
#define IRRTA      IRR1_BIT.b7                              /* Timer A Interrupt Request Flag */

#pragma interrupt (taint)
/*****
/* Function define
*****/
extern void INIT ( void );                                  /* SP Set
void      main ( void );
void      taint ( void );

/*****
/* Vector Address
*****/
#pragma section V1                                         /* Vector Section Set
void (*const VEC_TBL1[])(void) = {
    INIT                                                    /* 0x0000 Reset Vector
};
#pragma section V2                                         /* Vector Section Set
void (*const VEC_TBL2[])(void) = {
    taint                                                    /* 0x0016 timer A Interrupt Vector
};

#pragma section                                           /* P
/*****
/* Main Program
*****/
void main ( void )
{
    set_imask_ccr(1);                                       /* Interrupt Disable
    SYSCR1 = 0xE7;                                         /* Set SYSCR1
    SYSCR2 = 0xE0;                                         /* Set SYSCR2
    TMA = 0x1C;                                           /* Initialize TCA
    TMA = 0x1A;                                           /* Initialize TCA Overflow Period
    IRRTA = 0;                                            /* Clear IRRTA
    IENTA = 1;                                            /* Timer A Interrupt Enable
    set_imask_ccr(0);                                       /* Interrupt Enable
    sleep();                                               /* Transition to Sleep Mode
    while(1){
        ;
    }
}

```

```
/*-----*/  
/* Timer A Interrupt */  
/*-----*/  
void taint ( void )  
{  
    IRRTA = 0; /* Clear IRRTA */  
    IENTA = 0;  
}
```

Link address specifications

Section Name	Address
CV1	H'0000
CV2	H'001A
CV3	H'0026
P	H'0100
B	H'FB80

Revision Record

Rev.	Date	Description	
		Page	Summary
1.00	Dec.19.03	—	First edition issued

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